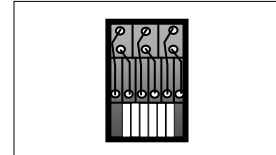
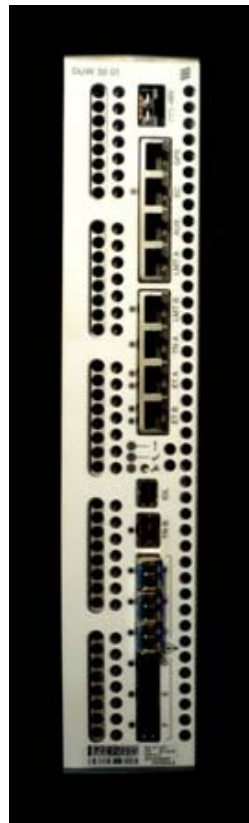


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## Ericsson W-CDMA/HSPA Baseband Unit KDU 127 161/3 R3C Model DUW30 01

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## TABLE OF CONTENTS

EXECUTIVE SUMMARY .....	5
Active/Passive Component Summary .....	5
<b>Important Note:</b> .....	5
CHAPTER 1: ERICSSON RBS6000 BTS SYSTEM .....	6
Overview of RBS6101/6102/6201/6202/6301/6601 Product Offering.....	6
CHAPTER 2: DUW MECHANICAL ANALYSIS .....	9
Mechanical Analysis.....	9
CHAPTER 3: BASEBAND PROCESSING BOARD SUBSYSTEM .....	17
Semiconductor Heat Sinks.....	25
CHAPTER 4: BOARD PROCESSOR AND RF/IF INTERFACE BOARD SUBSYSTEM .....	27
Semiconductor Heat Sinks.....	40
APPENDIX A - PASSIVE CASE SIZE ANALYSIS.....	42
APPENDIX B - ACTIVE COMPONENT MARKET SHARE ANALYSIS .....	46

# TABLES

Table 1: DUW Baseband Processor PCB Top Bill of Materials .....	22
Table 2: DUW Baseband Processor PCB Bottom Bill of Materials .....	24
Table 3: DUW Board Processor and RF/IF Top Bill of Materials .....	32
Table 4: DUW Board Processor and RF/IF Bottom Bill of Materials .....	38
Table 5: Passive Component Case Size Distribution by System Subsection .....	43
Table 6: Identified Passive Component Supplier Distribution by System Subsection.....	44
Table 7: Active/Passive Component Distribution by System Subsection.....	45
Table 8: Active Semiconductor/Component Vendor Distribution by System Subsection .....	47

# EXHIBITS

Exhibit 1: Ericsson RBS620x Macro Cell Indoor BTS System .....	7
Exhibit 2: Ericsson DUW System Block Diagram .....	7
Exhibit 3: DUW Unit, Front .....	9
Exhibit 4: DUW Unit, Back .....	10
Exhibit 5: DUW Unit, Side .....	10
Exhibit 6: DUW Unit, Top .....	11
Exhibit 7: DUW Unit, Bottom .....	11
Exhibit 8: DUW Frame, Top View .....	12
Exhibit 9: DUW Frame, Bottom View .....	12
Exhibit 10: DUW Frame, Rear View .....	13
Exhibit 11: DUW Top Shield, External View .....	14
Exhibit 12: DUW Top Shield, Internal View .....	14
Exhibit 13: DUW Bottom Shield, External View .....	15
Exhibit 14: DUW Bottom Shield, Internal View .....	15
Exhibit 15: DUW Bottom Shield, Rear View .....	16
Exhibit 16: DUW 30 System, Exploded Side View .....	16
Exhibit 17: DUW Processor PCB. Top View .....	17
Exhibit 18: DUW Baseband Processing PCB Component Diagram 1, Top View .....	18
Exhibit 19: DUW Baseband Processing PCB Component Diagram 2, Top View .....	19
Exhibit 20: DUW Baseband Processing PCB Component Diagram, Bottom View .....	20
Exhibit 21: DUW Baseband Processing Block Diagram .....	21
Exhibit 22: Semiconductor IC Heat Sink Dimensions (23mm, 27mm, 35mm) .....	25
Exhibit 23: Semiconductor IC Heat Sink Dimensions, 27mm .....	26
Exhibit 24: Semiconductor IC Heat Sink Dimensions, 35mm .....	26
Exhibit 25: DUW Board Processor and RF/IF PCB. Top View .....	27
Exhibit 26: DUW Board Processor and RF/IF PCB. Top View Component Diagram 1 .....	28
Exhibit 27: DUW Board Processor and RF/IF PCB. Top View Component Diagram 1 .....	29
Exhibit 28: DUW Board Processor and RF/IF Block Diagram .....	30
Exhibit 29: Baseband to RF/IF Connection .....	31
Exhibit 30: DUW Board Processor and RF/IF PCB. Bottom View Component Diagram .....	37
Exhibit 31: Semiconductor IC Heat Sink Dimensions (23mm, 27mm, 35mm) .....	40
Exhibit 32: Semiconductor IC Heat Sink Dimensions, 35mm .....	41
Exhibit 33: Semiconductor IC Heat Sink Dimensions, 41mm .....	41
Exhibit 34: Passive Component Case Size Distribution .....	42
Exhibit 35: Identified Passive Component Market Share by Vendor .....	45
Exhibit 36: Active Semiconductor Component Share .....	46
Exhibit 37: High Pin Count IC vs. Discretes .....	48
Exhibit 38: Active Semiconductor Market Share by Vendor .....	48
Exhibit 39: High Pin Count (64+) Active Semiconductor Market Share by Vendor .....	49